

Appl. No. 10/538,248
Reply to Office Action of: April 18, 2006

Attorney Docket No. 10555-103

II. Remarks

Reconsideration and re-examination of this application in view of the above amendments and the following remarks is herein respectfully requested.

After entering this amendment, claims 1-27 remain pending.

Allowable Subject Matter

The undersigned acknowledges the Examiner's Indication of the allowance of claims 1-15 and the allowability of claims 20 and 22-27, if rewritten into independent form, including all of the limitations of any base claims.

Accordingly, claim 22 has been rewritten into independent form so as to include all of the limitations of its base claim and any intervening claims. It is noted that claims 23-27 depend from claim 22. In view of this, it is submitted that these claims are allowable and such action is requested.

Further Claim Clarifications

Prior to discussing the rejections and references, it is believed that a brief discussion of the invention is warranted. The invention of this application relates to the use of solder glass in forming a fiber optic attachment. Previously metalized fibers and metal solder were required in order to form the attachment. These metalized fibers and solder add significant expense to the attachment. With the present invention, metalized fibers are not required. To achieve this, solder glass secures the optic fiber to a hot pad.

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Claim Rejections - 35 U.S.C. § 102(b)

Claims 16, 17, 19 and 21 were rejected under 35 U.S.C. § 102(b) as being anticipated by U.S. Publication No. 2003/0108304, to Ziari et al. ("Ziari"). Applicant respectfully traverses these rejections.

As noted above, the claims of the present application require solder glass and a hot pad. A review of Ziari reveals that neither are present in the reference. First, like the prior construction discussed in the application, Ziari's construction employs use of a metal solder, not glass solder. As noted in the paragraph [0030] the solder is AnSn and other suitable solders include PbSn and AuGe. Additionally, Ziari also does not employ a hot pad as claimed. As defined by the present application, the hot pad includes heating elements and serves as a hot plate over which the solder glass is melted. In Ziari metal solder is melted and fuses with another metal layer, the solder wetting layer 60a, of the fiber bonding pad 50. This wetting layer 60a is thus preferably made of Au or other similar materials to enhance fusing with the solder. With a hot pad as claimed, the solder glass does not fuse, by way of dissolution of the two similar metals into each other, with a top surface of a similar material. Rather, the solder glass bonds to the top surface. From this, it is submitted that Ziari fails to disclose the claimed invention and the rejection based thereon should be accordingly withdrawn.

Claim Rejections - 35 U.S.C. §103(a)

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Claim 18 was rejected under 35 U.S.C. § 103(a) as being unpatentable over Ziari. Since claim 18 ultimately is dependent on claim 16, claim 18 is also allowable for at least the same reasons as claimed in 16 noted above.

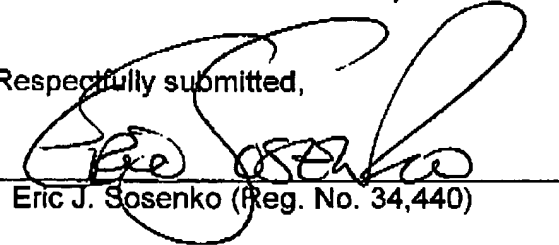
It is submitted that rejection under § 103 should therefore be withdrawn.

Conclusion

In view of the above amendments and remarks, it is respectfully submitted that the present form of the claims are patentably distinguishable over the art of record and that this application is now in condition for allowance. Such action is requested.

Respectfully submitted,

July 18, 2006
Date



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Attachment: None

EJS/alr